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ASSIGNMENT

WHEREAS, We, Michinari MIYAGAWA, a Japanese citizen, residing at 5-8, Mitsuyacho, Nagahama-shi, Shiga 526-8660, Japan and Takashi IMAI, a Japanese citizen, residing at 5-8, Mitsuyacho, Nagahama-shi, Shiga 526-8660, Japan, have invented certain new and useful improvements in a CONDUCTIVE RESIN FILM, COLLECTOR AND MANUFACTURING PROCESS THEREFOR for which we have executed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, Mitsubishi Plastics, INC. (hereinafter "ASSIGNEE"), a Japanese Corporation, with its principal place of business at 5-2, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-0005 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This _____ day of December 8, 2004

Michinari Miyagawa
Michinari MIYAGAWA

This _____ day of December 8, 2004

Takashi Imai
Takashi IMAI

Witness

Etsuro Yamaguchi
Etsuro YAMAGUCHI